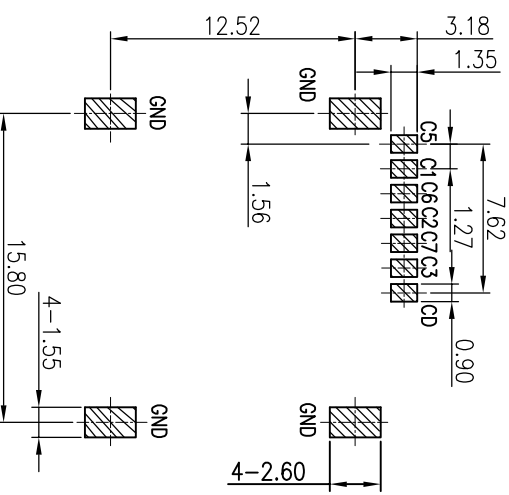


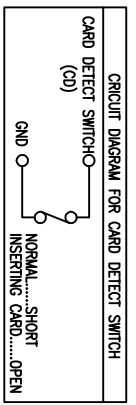
SIM pin Assignment	PIN#	Name
	C1	VCC
	C2	RST
	C3	CLK
	C5	GND
	C6	VPP
	C7	I/O



■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

NOTES:
MATERIAL:
 Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 Shell: STAINLESS
PLATING:
 Contact: Plated 30u" Ni Overall, Solder Area: Tin, Contact g/f
 Shell: Plated 30u" Ni Overall
 Plated g/f/ Selective Contact Area

Electrical:
 Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩ max.
 Insulation Resistance:1000MΩ min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Molding Cycles:5,000 Insertions
 Temperature: 260°C ±5



UNITS: mm		CSCONN	
GENERAL TOLERANCE		PART NO.(INTENDED USE)	
X. ±5°	0. X±0.25	CS107127135005	
X.1±2°	0. X1±0.2	APPD:	
X.X±1°	0. XX±0.1	CHKD:	Ski1a
		DR:	Kitty
TITLE:		DWG NO.	
MICRO SIM CARD 7P PUSH 1.35H 外焊式		SIM CARD	
SCALE	SHEET	REV	
1:1	1 OF 1	A	

CSCONN PRECISE ELECTRONICS CO.,LTD